

PATENTS  
112055-0040P1  
17732-38560.001

**IN THE CLAIMS:**

- 1 1. (currently amended) A die containing package comprising:  
2 a die defining electrical die contacts,  
3 a substrate defining first substrate contacts,  
4 flattened electrical conductive balls attached to the die contacts and making electri-  
5 cal connection thereto,  
6 electrical conductive runs on the substrate connecting the first substrate contacts to  
7 second substrate contacts, wherein the second substrate contacts are located on the sub-  
8 strate opposite the first substrate contacts,  
9 electrically conductive wires with first ends making electrical connections to the  
10 first substrate contacts, wherein the wires are formed to run substantially parallel to the  
11 surface of the die, and wherein the other ends are horizontally attached to the flattened  
12 balls.
- 1 2-3. canceled.
- 1 4. (previously presented) The die containing package of claim 1 wherein the second sub-  
2 strate contacts are located on the substrate to accommodate a pin out different from the die.
- 1 5. (currently amended) A process for packaging a die comprising the steps of:  
2 defining electrical die contacts,  
3 defining a substrate with first substrate contacts,  
4 flattening electrical conductive balls,  
5 attaching the flattened electrically conductive balls to the die contacts,

PATENTS  
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17732-38560.001

6 forming electrical conductive runs on the substrate connecting the first substrate  
7 contacts to second substrate contacts, wherein the second substrate contacts are located on  
8 the substrate opposite the first substrate contacts.  
9 connecting electrically conductive wires to the first substrate contacts,  
10 running the electrically conductive wires substantially parallel to the surface of the  
11 die to the die contacts, and  
12 horizontally attaching the other ends of the wires to the flattened electrical conductive balls  
13 thereby making electrical connections therebetween, and wherein the other ends remain  
14 substantially parallel to the surface of the die .

1 6-7. canceled.

1 8. (previously presented) The process of claim 5 further comprising the step of locating  
2 the second substrate contacts on the substrate to accommodate a pin out different from the  
3 die.